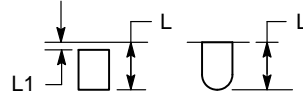




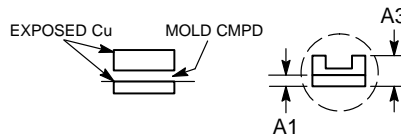
WDFN6 3x3, 0.95P  
CASE 511AP i01  
ISSUE O

DATE 12 MAY 2009

SCALE 2:1

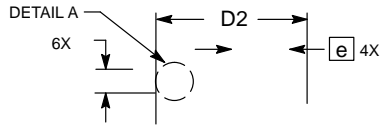
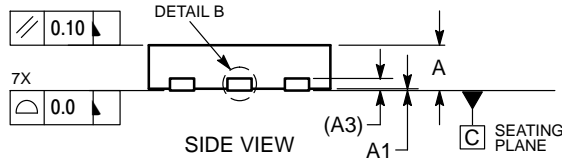


DETAIL A  
ALTERNATE TERMINAL  
CONSTRUCTIONS



DETAIL B  
ALTERNATE  
CONSTRUCTIONS

DIM	MILLIMETERS	
	MIN	MAX
A	0.70	0.80
A1	0.00	0.05
A3	0.20	REF
b	0.35	0.45
D	3.00	BSC
D2	2.40	2.60
E	3.00	BSC
E2	1.50	1.70
e	0.95	BSC
K	0.20	iii
L	0.30	0.50



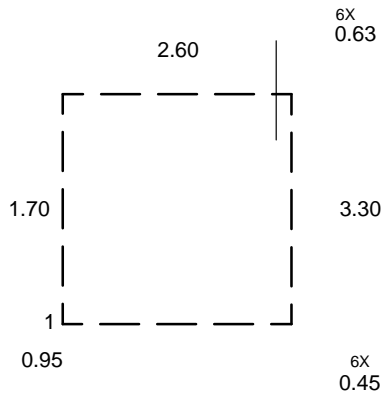
6X K-

6 4



GENERIC  
MARKING DIAGRAM\*

- XXXX = Specific Device Code
  - A = Assembly Location
  - Y = Year
  - WW = Work Week
  - = Pb iFree Package
- (Note: Microdot may be in either location)



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb iFree strategy and soldering details, please download the ON Semiconductor Strategy ask g Te